

MESD01G/MESD02G/MESD04G

SD NAND

Datasheet

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1. Introduction

MengXW SD NAND is an embedded storage solution designed in a LGA8 package form. The operation of SD NAND is similar to an SD card which is an industry standard.

SD NAND consists of NAND flash and a high performance controller. 3.3V supply voltage is required for the NAND area (VCC). SD NAND is fully compliant with SD2.0 interface, which allows most of general CPU to utilize. SD NAND has high performance at a competitive cost, high quality and low power consumption.

2. Product List

| Capacity | Part number | Package | Size |
|----------|-------------|-----------------------|-------|
| 1Gb | MESD01GLGEG | LGA8 (Land GridArray) | 8x6mm |
| 2Gb | MESD02GLGEG | LGA8 (Land GridArray) | 8x6mm |
| 4Gb | MESD04GLGEG | LGA8 (Land GridArray) | 8x6mm |

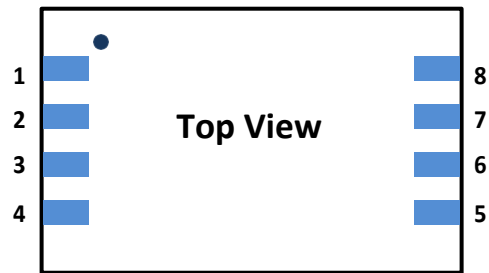
3. Features

- Support up to 50Mhz clock frequency
- Support 1/4 bit mode
- Built-in HW ECC Engine and highly reliable NAND management mechanism
- Write speed up to class 8
- Smaller package LGA8 (Land GridArray)

4. Physical Characteristic Temperature

- Operation Conditions
Temperature Range: Ta = -30 to +85 degrees centigrade
- Storage Conditions
Temperature Range: Tstg = -40 to +85 degrees centigrade

5. Pin Assignments



| Pin No. | Pin name (SD mode) | Pin name (SPI mode) |
|---------|---------------------|---------------------|
| 1 | SD2, I/O pin | NC, no connection |
| 2 | SD3, I/O pin | /CS, chip select |
| 3 | CLK, clock signal | CLK, clock signal |
| 4 | Vss, ground | Vss, ground |
| 5 | CMD, command signal | DI, data in |
| 6 | SD0, I/O pin | DO, data out |
| 7 | SD1, I/O pin | NC, no connection |
| 8 | Vdd, power supply | Vdd, power supply |

6. Usage

Product Protocol

As SD NAND is the realize SD2.0 standard product, thus please refer to the SD2.0 related protocol : SD Physical Layer Specification Version 2.00.

DC Characteristics

| Item | Symbol | MIN | MAX | Unit | Note | |
|--------------------------|------------------|-----------------|------------------------|------------------------|--|---|
| Supply voltage | VDD | 2.7 | 3.6 | V | | |
| Input voltage | High Level | V _{IH} | V _{DD} *0.625 | V _{DD} +0.3 | V | |
| | Low Level | V _{IL} | V _{SS} -0.3 | V _{DD} *0.25 | V | |
| Output voltage | High Level | V _{OH} | V _{DD} *0.75 | -- | V | I _{OH} =-2mA, V _{DD} =V _{DDmin} |
| | Low Level | V _{CL} | -- | V _{DD} *0.125 | V | I _{OL} =2ma, V _{DD} =V _{DDmin} |
| Standby Current(*) | I _{cc1} | -- | 20* | mA | V _{DD} =3.6V, clock 25MHz V _{DD} =3.0V, clock STOP, T _a =25° C | |
| | | -- | 0.2 | | | |
| Operation Current(*) | Write | I | -- | 30 | mA | 3.6V/25MHz,50MHz |
| | Read | I | -- | 30 | | |
| Input voltage setup Time | V _{rs} | -- | 250 | ms | | |

Note: Standby current max 20mA with CLOCK 25Mhz only based on 100 pcs samples

Peak Voltage and Leak Current

| Item | Symbol | MIN | MAX | Unit | Note |
|--|--------|------|----------------------|------|------|
| Peak voltage on all lines | | -0.3 | V _{DD} +0.3 | V | |
| Input Leakage Current for all pins | | -10 | 10 | uA | |
| Output Leakage Current for all outputs | | -10 | 10 | uA | |

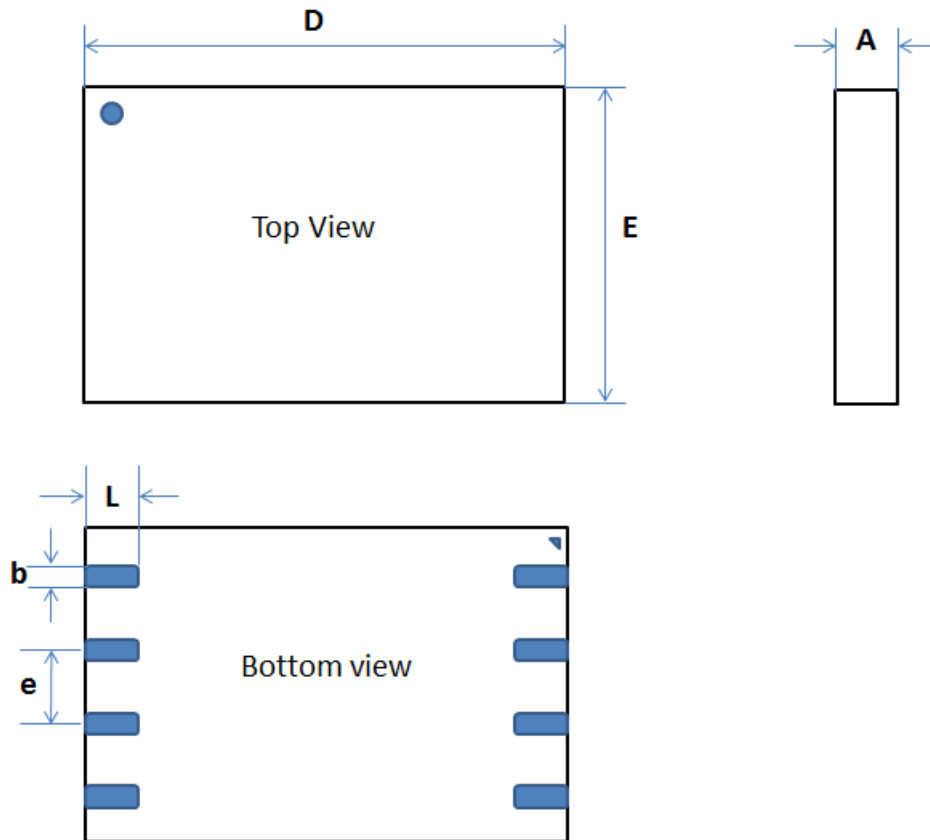
Signal Capacitance

| Item | Symbol | MIN | MAX | Unit | Note |
|--|------------------------------------|-----|-----|------|--|
| Pull up Resistance | R _{CMD} /R _{DAT} | 10 | 100 | k | |
| Total bus capacitance for each signal line | C _L | - | 40 | pF | 1 card C _{HOST} +C _{BUS} ≤ 30pF |
| Card Capacitance for signal pin | C _{CARD} | - | 10 | pF | |
| Pull up Resistance inside card (pin1) | R _{DAT3} | 10 | 90 | k | |
| Capacity Connected to Power line | C _C | - | 5 | pF | |

Note: WP pull-up (R_{wp}) Value is depend on the Host Interface drive circuit.

7. Package Dimensions

LGA8 (8*6mm) (Land Grid Array)



Dimensions

| Symbol | | A | | b | D | | E | | e | | L |
|--------|------|------|--|------|------|--|------|--|------|--|------|
| Unit | | | | | | | | | | | |
| Mm | Min | 0.85 | | 0.55 | 7.95 | | 5.95 | | | | 0.75 |
| | Norm | 0.90 | | 0.60 | 8.00 | | 6.00 | | 1.27 | | 0.80 |
| | Max | 0.95 | | 0.65 | 8.05 | | 6.05 | | | | 0.85 |

8. Ordering Information

The ordering part number is formed by a valid combination of the following

